

RELIABILITY REPORT  
FOR  
MAX3081EESA+  
PLASTIC ENCAPSULATED DEVICES

October 1, 2013

**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

<b>Approved by</b>
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## Conclusion

The MAX3081EESA+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX3080E&#150;MAX3089E are  $\pm 15\text{kV}$  electrostatic discharge (ESD)-protected, high-speed transceivers for RS-485/RS-422 communication that contain one driver and one receiver. These devices feature fail-safe circuitry, which guarantees a logic-high receiver output when the receiver inputs are open or shorted. This means that the receiver output will be a logic high if all transmitters on a terminated bus are disabled (high impedance). The MAX3080E/MAX3081E/MAX3082E feature reduced slew-rate drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free data transmission up to 115kbps. The MAX3083E/MAX3084E/MAX3085E offer higher driver output slew-rate limits, allowing transmit speeds up to 500kbps. The MAX3086E/MAX3087E/MAX3088Es' driver slew rates are not limited, making transmit speeds up to 10Mbps possible. The MAX3089E's slew rate is selectable between 115kbps, 500kbps, and 10Mbps by driving a selector pin with a single three-state driver. All devices feature enhanced ESD protection. All transmitter outputs and receiver inputs are protected to  $\pm 15\text{kV}$  using the Human Body Model. These transceivers typically draw  $375\mu\text{A}$  of supply current when unloaded, or when fully loaded with the drivers disabled. All devices have a 1/8-unit-load receiver input impedance that allows up to 256 transceivers on the bus. The MAX3082E/MAX3085E/MAX3088E are intended for halfduplex communications, while the MAX3080E/MAX3081E/MAX3083E/MAX3084E/MAX3086E/MAX3087E are intended for full-duplex communications. The MAX3089E is selectable between half-duplex and full-duplex operation. It also features independently programmable receiver and transmitter output phase via separate pins.

## II. Manufacturing Information

A. Description/Function:	±15kV ESD-Protected, Fail-Safe, High-Speed (10Mbps), Slew-Rate-Limited RS-485/RS-422 Transceivers
B. Process:	B3
C. Number of Device Transistors:	631
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand, Philippines, or Malaysia
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1901-0156
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

## IV. Die Information

A. Dimensions:	136X85 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)  
Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{1000 \times 4340 \times 77 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 2.74 \times 10^{-9}$$

$$\lambda = 2.74 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.03 @ 25C and 0.57 @ 55C (0.8 eV, 60% UCL).

### B. E.S.D. and Latch-Up Testing (lot ND9BCA9A4G, D/C 0839)

The RS46-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-100mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX3081EESA+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 1000 hrs.	DC Parameters & functionality	77	0	ND9FC25A8C, D/C 0802

Note 1: Life Test Data may represent plastic DIP qualification lots.